

JAN 16 2004
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 09/784,234
Filing Date February 14, 2001
Inventor Shozo Nagano et al.
Assignee Honeywell International Inc.
Group Art Unit 1742
Examiner Ip, Sikyin
Attorney Docket No. 30-5000-(4015)-DIV1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating
Anodes, Metal Alloys for Use as a Conductive Interconnection In an Integrated
Circuit, and Physical Vapor Deposition Targets

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NUMBER OF PAGES IN FACSIMILE: 7

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RESPONSE TO NOVEMBER 18, 2003 FINAL OFFICE ACTION

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AMENDMENTS**Introductory Comments**

In reply to the Final Office Action dated November 18, 2003, applicant amends and
remarks as follows.